## AEROSPACE DATA EXCHANGE PROGRAM TRANSMITTAL



# **PROBLEM ADVISORY**

1. TITLE			2. DOCUMENT NU	2. DOCUMENT NUMBER					
MICROCIRUIT, MEMORY, DIGITAL, CMOS, 512K X 32-BIT (16M) WITH EMBEDDED EDAC, RADIATION-HARDENED LOW VOLTAGE SRAM, MONOLITHIC SILICON				SPO-2012-PA-0001					
			3. DATE (Year, Mo						
4 MANUEACTUR	ER NAME AND ADDRESS			2012, October, 04  5. MANUFACTURER POINT OF CONTACT NAME					
CAES			Mike Leslie						
	NNIAL BOULEVARD SPRINGS, COLORADO	O 80907-3486		ER POINT OF CONTAC	TTELEPHONE				
OOLON IDO	or raines, colorado	0 00007 0400		(719) 594-8148  7. MANUFACTURER POINT OF CONTACT EMAIL					
					I EMAIL				
8. CAGE CODE 9. LDC START 10. LDC END				Mike.Leslie@cobhamaes.com  11. PRODUCT IDENTIFICATION CODE   12. BASE PART					
65342		ALL	WC04 / WC05		UT8ER512K32M/S				
13. BLANK			14. SMD NUMBER	2	15. DEVICE TYPE DESIGNATOR				
			5962-06261		TYPE (01-06)				
_			16. RHA LEVELS		17. QML LEVEL				
			R		Q, V				
_			18. NON QML LEV	/EL	19. BLANK				
			HiRel, Protos						
20. PROBLEM DE	SCRIPTION / DISCUSSION / E	EFFECT							
settings. An incorrect test method resulted in inaccurate initial characterization data.									
		_							
verify comp	methodology has I pliance with the inc LAX specifications o	reased 400ns n	ninimum specifica	tion. Additiona	ılly, parameters				
CAES is working in coordination with DLA Land and Maritime to effect the changes referenced in this ADEPT to the SMD, which is currently at revision level B.									
The propos this GIDEP	ed list of SMD cha	nges related to	parameters $t_{CHAV}$ ,	$t_{CLAX}$ , and $t_{AVCL}$	are appended to				
Fielded uni	ts are guaranteed l	by design to me	eet these paramete	ers, no field ret	urns are planned				
	IARY RECOMMENDATION:	USE AS IS	CONTACT	REMOVE &	<u> </u>				
		USE AS IS	MANUFACTURER	REPLACE	CHECK & 🗵				
23. ADEPT REPR	PESENTATIVE	24. SIGNATURE			USE AS IS 25. DATE				
<u>_</u>									
Timothy L. Meade Simothy Meade					04, October, 2012				

## TABLE IA. Electrical performance characteristics (sheet 10)

#### **Previous:**

Test	Symbol	Test condition	Group A	Device	Limits		Units
			subgroups	Type	min	max	
Address valid to control low	tavcl		9,10,11	All	200		ns

## **Corrected:**

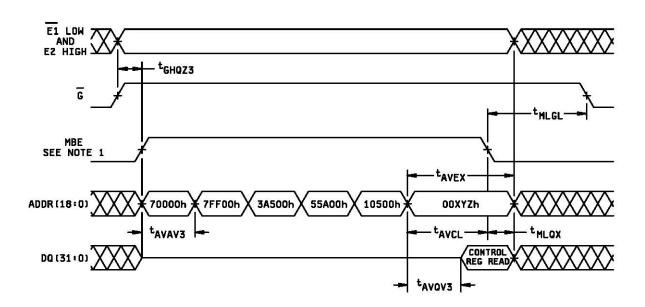
Test	Symbol	Test condition	Group A	Device	Limits		Units
			subgroups	Type	min	max	
Address valid to control low	tavcl		9,10,11	All	400		ns

## Added parameter to TABLE IA. Electrical performance characteristics (sheet 10)

Test	Symbol	Test condition	Group A	Device	Limits		Units
			subgroups	Type	min	max	
MBE high to address valid	t <sub>CHAV</sub>		9,10,11	All	0		ns
MBE low to address invalid	t <sub>CLAX</sub>		9,10,11	All	0		ns

## FIGURE 5. Timing waveforms - Continued (sheet 22)

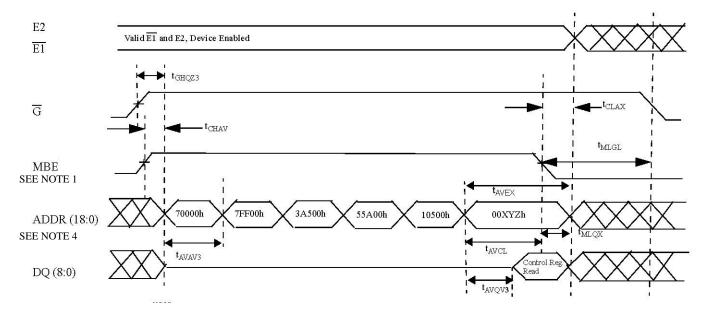
## **Previous:**



#### Notes:

- 1. MBE is driven high by the user.
- 2. Lower 9 bits of the last address are used to read or configure the control register (see vendor data sheet)
- 3. SCRUB ≥ Voн before the start of the configuration cycle. Ignore SCRUB during configuration cycle.

## **Corrected:**



#### Notes:

- 1. MBE is driven high by the user.
- 2. Lower 10 bits of the last address are used to read or configure the control register (see vendor data sheet)
- 3. SCRUB ≥ VoH before the start of the configuration cycle. Ignore SCRUB during configuration cycle.
- 4. Device must see a transition to address 70000h coincident with or subsequent to MBE assertion.

EDAC Control register cycle